

In the Specification:

[0002] A known integrated circuit (IC) package, with an exposed die attach pad (DAP), is shown in Fig. 1. IC package 10 consists of IC die 12 mounted on die attach pad 16 14 by means of a die attach epoxy 14 16. IC die 12 is coupled to the input/output pins of metal lead frame 18 by means of a plurality of bond wires 20. A molded IC body 22 is then formed around IC die 12 and lead frame 18 in a known manner to complete the package. As shown in Fig. 1, lower surface 15 of die attach pad 16 14 remains exposed and co-planar with the leads of lead frame 18 after IC package 10 is completed.